



TABLE 1

Variant	Label text
001	
002	

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP8921	REV: A	SVN REV: Not In VersionControl
IGNORE -> Top Overlay			
PLOT NAME = Top Assembly Drawing	GENERATED : 3/20/2013 9:06:33 AM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP8921	REV: A	SVN REV: Not In VersionControl
	IGNORE -> Bottom Overlay		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 3/20/2013 9:06:33 AM	TEXAS INSTRUMENTS	

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